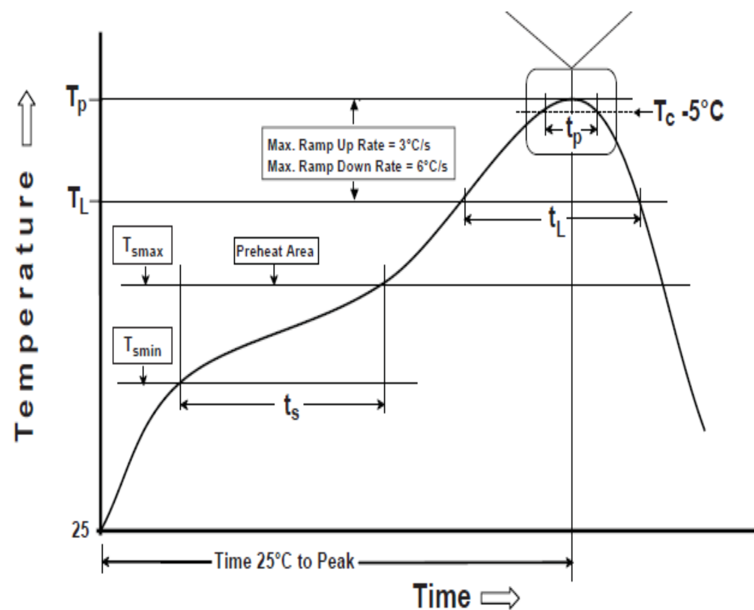

SMT Profile

Profile Feature	SMT Component Spec
Preheat/Soak **Temperature Min (Tsmin)** **Temperature Max (Tsmax)** **Time (ts) from (Tsmin to Tsmax)**	 150 °C 200 °C need endure 120 seconds
Ramp-up rate (TL to Tp)	need endure 3 °C/second max.
Liquidous temperature (TL) **Time (tL) maintained above TL**	217 °C need endure 90 seconds
Peak package body temperature (Tp)	260 °C
Time (tp)* within 5 °C of the specified classification temperature (Tc), see the pic above	need endure 10* seconds
Ramp-down rate (Tp to TL)	need endure 6 °C/second max.
Time 25 °C to peak temperature	need endure 8 minutes max.

Note 1: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow (e.g., live-bug). If parts are reflowed in other than the normal live-bug assembly reflow orientation (i.e., dead-bug), Tp shall be within ± 2 °C of the live-bug Tp and still meet the Tc requirements, otherwise, the profile shall be adjusted to achieve the latter. To accurately measure actual peak package body temperatures
refer to JEP140 for recommended thermocouple use.

Note 2 : For SMT type component, it need be able to withstand twice times SMT Reflow + once DIP Wave soldering process.

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